

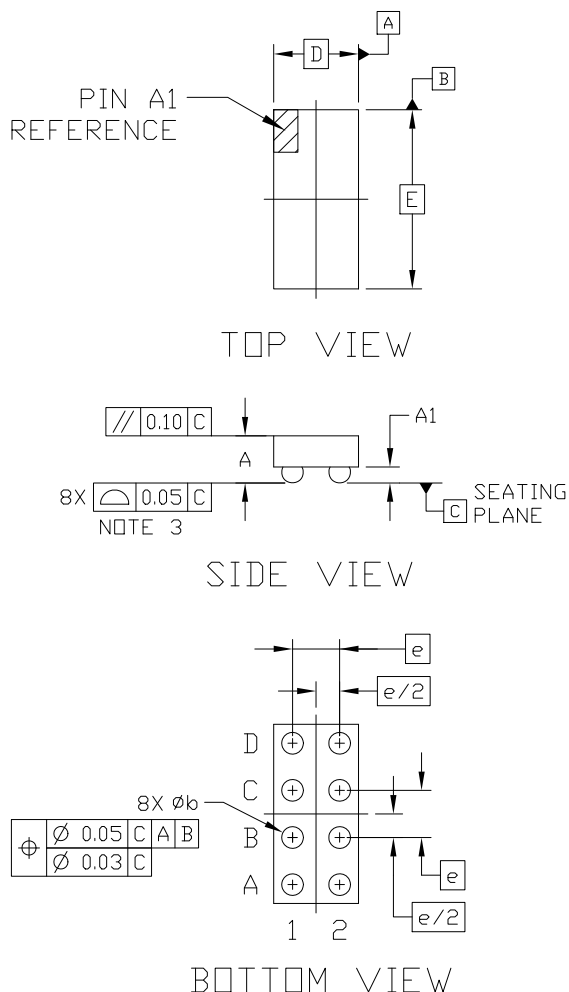
MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



SCALE 4:1

8 PIN FLIP-CHIP, 0.9x1.9, 0.5P CASE 499BF ISSUE A

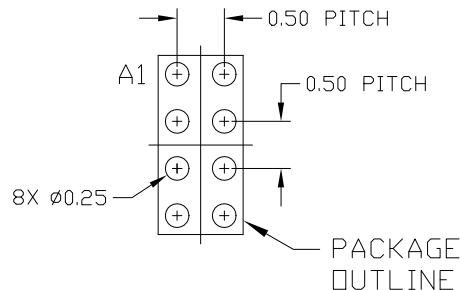
DATE 12 JAN 2022



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

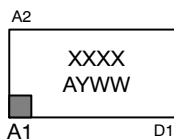
DIM	MILLIMETERS	
	MIN	MAX
A	0.44	0.50
A1	0.18	0.22
b	0.24	0.28
D	0.90 BSC	
E	1.90 BSC	
e	0.50 BSC	



SOLDERING FOOTPRINT*

*For additional information on our Pb-Free strategy and soldering details, please download the onsemi soldering and mounting techniques reference manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



XXXX = Specific Device Code
A = Assembly Location
Y = Year
WW = Work Week

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	8 PIN FLIP-CHIP, 0.9X1.9, 0.5P	PAGE 1 OF 1

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